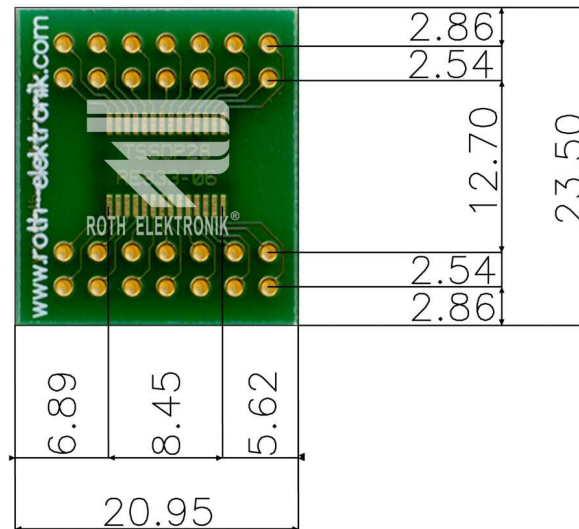


#### RE933-06

- Epoxy fibre-glass FR4 1.50 mm
  - Double-sided 35 µm Cu
  - Plated through holes (PTH)
  - Surface chem. Ni/Au with solder stop mask
  - Adaption circuit board for TSSOP 28
  - Pitch: 0.65 mm (173 mil)
  - Hole diameter 1.00 mm
  - Size 20.95 x 23.50 mm
- Module-No. Pitch mil Pin Size (mm)

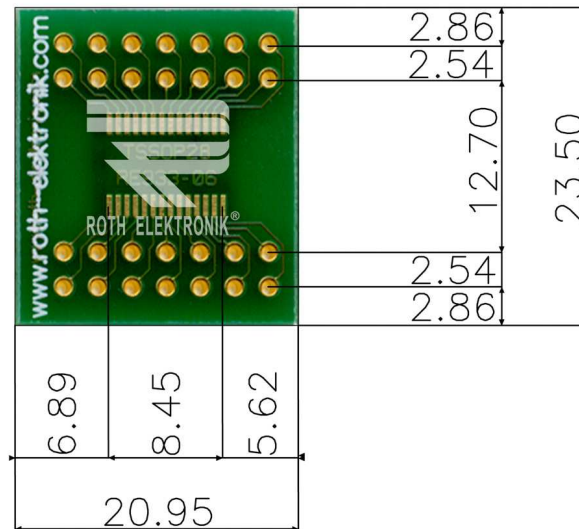
RE933-06 0.650 mm 22.5 28 4.400 (173 mil)



#### RE933-06

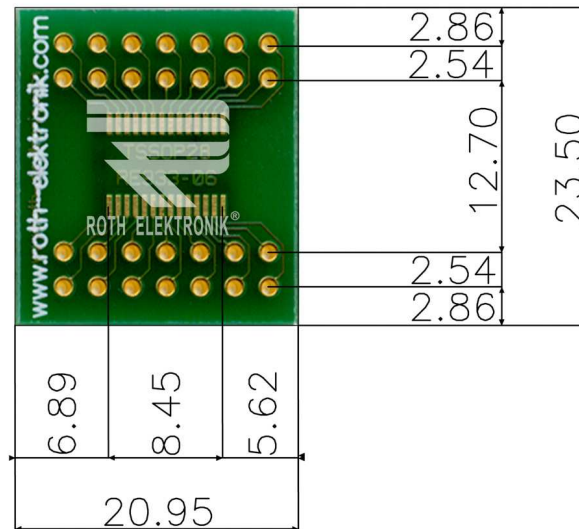
- Epoxydglashartgewebe FR4 1,50 mm
  - Zweiseitig 35 µm Cu
  - Durchkontaktiert (PTH)
  - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
  - Adaptionsplatine für TSSOP 28
  - Pitch: 0,65 mm (173 mil)
  - Lochdurchmesser 1,00 mm
  - Größe 20,95 x 23,50 mm
- Modul-Nr. Pitch mil Pin Größe (mm)

RE933-06 0,650 mm 22,5 28 4,400 (173 mil)



#### RE933-06

- Fibre de verre époxyde FR4 1,50 mm
  - Double face 35 µm Cu
  - Métallisation des trous (PTH)
  - Surface avec Ni/Au chimique et un laque d'arrêt de soudure
  - Platine d'adaptation pour TSSOP 28
  - Pitch: 0,65 mm (173 mil)
  - Perforation 1,00 mm Ø
  - Dimensions 20,95 x 23,50 mm
- Module-No. Pitch mil Pin Dimensions (mm)  
RE933-06 0.650 mm 22,5 28 4,400 (173 mil)



#### RE933-06

- Fibra de vidrio epoxídica FR4 1,50 mm
  - Por dos lados 35 µm de Cu
  - Agujeros con contactos metalizados (PTH)
  - Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
  - Adaptador para TSSOP 28
  - Pitch: 0,65 mm (173 mil)
  - Diámetro de agujeros 1,00 mm
  - Tamaño 20,95 x 23,50 mm
- Módulo-No. Pitch mil Pin Tamaño (mm)

RE933-06 0.650 mm 22.5 28 4.400 (173 mil)